Product Change Notification

104205 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: **104205 - 00**
Change Title: **Optical Networking, LXT16713A and LXT16723, PCN 104205-00, FYI**
Date of Publication: **July 1, 2004**

Type of Change Notification:

FYI - (For Your Information)

Key Characteristics of the Change:

Documentation

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 1, 2004

Description of Change to the Customer:

The package drawing in the datasheet for the Intel LXT16713A Rev. 006 and LXT16723 Rev. 002 4x4mm QFN package describes the heat sink dimensions as a 2.60mm ± .100mm sq exposed pad with tie bars. The correct information should have been 2.71mm ± 0.140mm sq. exposed tie bars, see diagrams below.

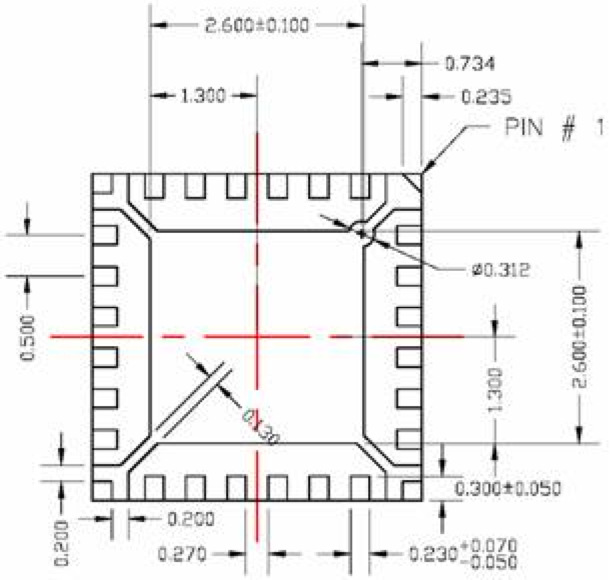

Diagram 1 – 4x4mm QFN package with heat sink dimension as a 2.60mm ±0.100mm sq exposed pad with tie bars (incorrect information for LXT16713A and LXT16723)

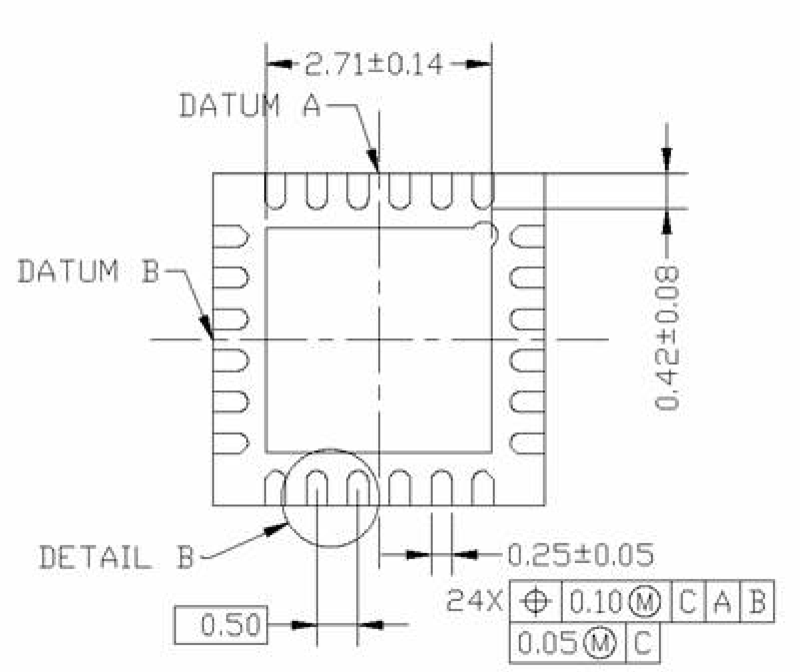

Diagram 2 – 4x4mm QFN package with heat sink dimension as a 2.71mm ± 0.140mm sq exposed pad without tie bars (correct information for the Intel LXT16713A and LXT16723)

Customer Impact of Change and Recommended Action:

Intel recommends that customers review their PCB traces below, and or around any of the effected components to avoid potential short circuit.

Products Affected / Intel Ordering Codes:

Component Product Table

Product Code	MM#
LBLXT16713A	856069
LBLXT16723NC	857704

Reference Documents / Attachments:

Document:	Location #:

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
July 1, 2004	00	Originally Published PCN